

1 WHAT IS CLAIMED IS:

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1. A method of mounting a semiconductor device having bumps on a board having pads so that each of said bumps is joined to a corresponding one of said pads, an adhesive to be hardened by heat being provided between said semiconductor device and said board, said method comprising the steps of:

(a) pressing said bumps of said semiconductor device on said pads of said board; and

(b) heating a portion in which each of said bumps and a corresponding one of said pads are in contact with each other, wherein pressure of said bumps against said pads reaches a predetermined value before a temperature of said adhesive to which heat is supplied in step (b) reaches temperature at which said adhesive is hardened.

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2. A method of mounting a semiconductor device having bumps on a board having pads so that each of said bumps is joined to a corresponding one of said pads, an adhesive to be hardened by heat being provided between said semiconductor device and said board, said method comprising the steps of:

(a) causing a head heated at a temperature at which said adhesive is hardened to press said semiconductor device on said board so that each of said bumps is pressed on a corresponding one of said pads, wherein pressure of said bumps against said pads reaches a predetermined value before a temperature of said adhesive to which heat is supplied from said head

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1 reaches temperature at which said adhesive is
hardened; and

(b) releasing said head from pressing said
semiconductor device after said adhesive is completely
5 hardened.

10 3. A method of mounting a semiconductor
device having bumps on a board having pads so that
each of said bumps is joined to a corresponding one of
said pads, an adhesive to be hardened by heat being
provided between said semiconductor device and said
15 board, said method comprising the steps of:

(a) providing a member between said
semiconductor device and said board, said member
having a thermal characteristic of delaying
transmission of heat;

20 (b) causing a head heated at a temperature
at which said adhesive is hardened to press said
semiconductor device against said board via said
member so that each of said bumps is pressed against a
corresponding one of said pads, wherein the
25 transmission of the heat from said head to said
adhesive is delayed by said member so that pressure of
said bumps against said pads reaches a predetermined
value before a temperature of said adhesive to which
heat is supplied from said head reaches a temperature
30 at which said adhesive is hardened; and

(c) releasing said head from pressing said
semiconductor device after said adhesive is completely
hardened.

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1 4. The method as claimed in claim 3,
wherein said member is a sheet, and wherein said step
(a) has a step of:

5 (a-1) moving said sheet by one step after
said step (c) so that a new part of said sheet which
has not yet used is fed into a space between said
semiconductor device and said board.

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5. The method as claimed in claim 3,
wherein said member is selected from among a group
including a polyimide film sheet, a polyester film
sheet and a silicon film sheet.

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